

ABSTRACT OF THE DISCLOSURE

Polishing Pads Useful in Chemical Mechanical Polishing  
of Substrates in the Presence of a Slurry  
Containing Abrasive Particles

A polishing pad for polishing semiconductors and  
5 other planar substrates in the presence of a slurry  
comprising abrasive particles and a dispersive agent is  
disclosed. The polishing pad includes a soluble component,  
preferably fibrous, within a polymer matrix component. The  
fibrous component includes fibers soluble in the slurry  
10 sufficiently to provide a void structure in the polishing  
surface of the pad. The void structure enhances the  
polishing rate and uniformity by increasing the mobility  
of the abrasive particles while reducing scratching of the  
polished surface. Additives that further enhance polishing  
15 and/or assist in the removal of residues generated during  
polishing, such as surfactants and removers, are  
optionally incorporated in the fibrous substance or  
topographically coated on the fibrous substance.

20 Fig. 1